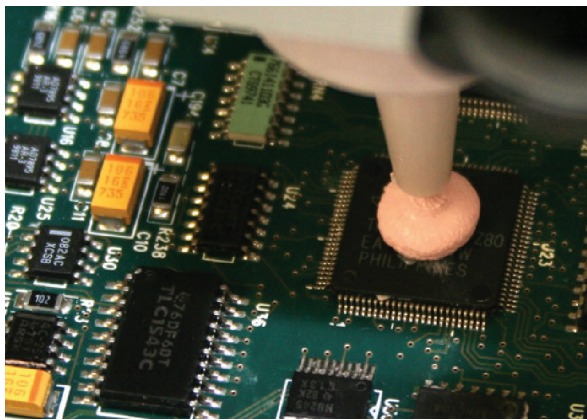


## THERM-A-GAP™ GEL 8010 & GEL 30

**THERM-A-GAP™** fully cured dispensable gels from Parker Chomerics eliminate time-consuming hand assembly, decreasing installation costs and reducing manufacturing and purchasing complexity.

### Common Applications

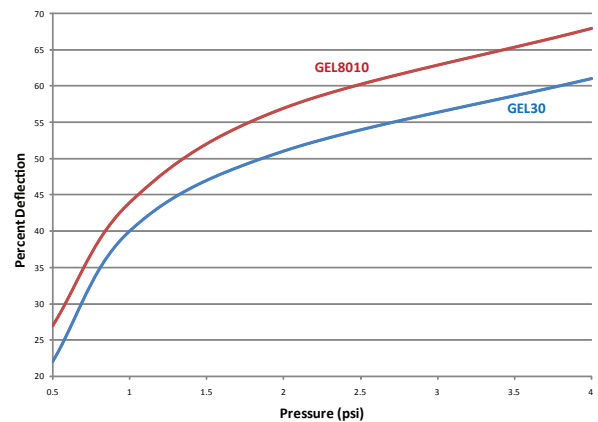
- Electronic Control Units
- Power Supplies & Semiconductors
- Memory & Power Modules
- Microprocessors / Graphics Processors
- Flat Panel Displays
- LED Lighting & Industrial Applications



THERM-A-GAP™ GELS result in much lower mechanical stress on delicate components than even the softest gap-filling sheets.

### VALUE PROPOSITION

- Easily dispensable and reworkable, which increases productivity and reduces installation costs.
- Improves cost efficiency due to low thermal impedance at thin and thick gaps, allowing use of common heat spreaders.
- Extends lifetime of the application:
  - Proven reliability in extreme temperatures and shock & vibration.
  - Deflects easily under low compressive force, creating less stress on components.



GEL 8010 & GEL 30  
Percent Deflection Vs. Pressure

## PRODUCT FEATURES

- Easily dispensable
- Fully cured / no pump out
- High bulk thermal conductivity
- Low thermal impedance
- Ultra low compression force
- High tack service and reworkable
- Proven long-term reliability
- Supplied in plastic syringes and aluminum cartridges

## OPERATING CONDITIONS

### GEL 8010

- Thin bond line gel (approximately 2-10 mils)
- Ideal for high-volume dispensing
- Can be stencil printed onto the plates

### GEL 30

- Used in many bond line thicknesses for application to multiple devices
- Excellent performance-to-price
- Compatible with high volume, automated dispense processes


Typical Properties		GEL 8010	GEL 30	Test Method
Physical	Color	White	Pink	Visual
	Flow Rate, grams/min - 30cc syringe with no tip attachment 0.100" orifice, 90psi (621 kPa)	60	20	Chomerics
	Specific Gravity	2.70	3.20	ASTM D792
	Percent Deflection @ Various Force Levels	% Deflection	% Deflection	Modified ASTM C165 Dispensed 1.0 cc of material Brought 1"x1" probe down to 0.100" Test rate 0.025 in/min
	Typical minimum bondline thickness, in (mm)	0.002 (0.05)	0.004 (0.10)	Chomerics
Thermal	Thermal Conductivity, W/m-K	3.0	3.5	ASTM D5470
	Heat Capacity, J/g-K	1	1	ASTM E1269
	Coefficient of Thermal Expansion, ppm/K	150	150	ASTM E831
	Operating Temperature Range, °F (°C)	-67 to 392 (-55 to 200)	-67 to 392 (-55 to 200)	Chomerics
Electrical	Dielectric Strength, Vac/mil (KVac/mm)	200 (8.0)	200 (8.0)	ASTM D149
	Volume Resistivity, ohm-cm	10 <sup>14</sup>	10 <sup>14</sup>	ASTM D257
	Dielectric Constant @100 kHz	6.3	7.0	ASTM D150
	Dielectric Factor @100 kHz	0.002	0.002	Chomerics
Regulatory	Flammability Rating	V-0	V-0	UL 94
	RoHS Compliant	Yes	Yes	Chomerics Certification
	Outgassing, % TML (CVCM)	1.33 (0.34)	0.15 (0.05)	ASTM E595
	Shelf Life, months from date of manufacture	18	18	Chomerics

For more information, contact your local Zatkoff representative or visit our website.

**Zatkoff**  
SEALS & PACKINGS

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ZSP P0002A 0119

 **WARNING:** This product contains a chemical known to the state of California to cause cancer, or birth defects or other reproductive harm. For more information go to [www.P65Warnings.ca.gov](http://www.P65Warnings.ca.gov).